

ABSTRACT OF THE DISCLOSURE:

**TITLE:       METHOD FOR TESTING MULTI-CHIP PACKAGES**

5       A specialized computer program is utilized to  
operate apparatus for testing internal components of an  
integrated circuit package. A Peltier-junction module is  
controlled so as to ramp-up and ramp-down the temperature  
10 of an integrated circuit package while reading out and  
plotting the power-bus-ground resistance of the package  
during the up-ramp and down-ramp cycles. The computer  
screen then indicates a characteristic graph for a  
properly working package and erratic graph for a package  
10 having a short circuit or open circuit components.

00531860-032100